UT62256

FEATURES

Access time : 35/70ns (max.)Low power consumption:

Operating : 60 mA (typical) Standby : 3mA (typical) normal

2 μA (typical) L-version 1 μA (typical) LL-version

■ Single 5V power supply

■ All inputs and outputs TTL compatible

■ Fully static operation

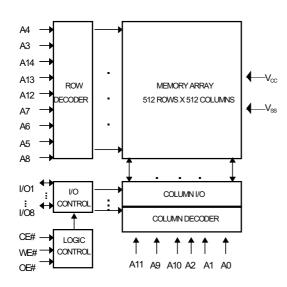
■ Three state outputs

■ Data retention voltage : 2V (min.)

■ Package : 28-pin 600 mil PDIP 28-pin 330 mil SOP

28-pin 330 mil SOP 28-pin 8x13.4mm TSOP-I

FUNCTIONAL BLOCK DIAGRAM



PIN DESCRIPTION

SYMBOL	DESCRIPTION
A0 - A14	Address Inputs
I/O1 - I/O8	Data Inputs/Outputs
CE#	Chip Enable Input
WE#	Write Enable Input
OE#	Output Enable Input
V_{CC}	Power Supply
V_{SS}	Ground

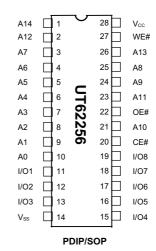
GENERAL DESCRIPTION

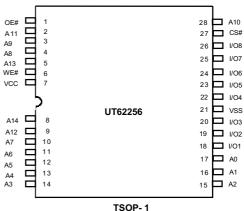
The UT62256 is a 262,144-bit low power CMOS static random access memory organized as 32,768 words by 8 bits. It is fabricated using high performance, high reliability CMOS technology.

The UT62256 is designed for high-speed and low power application. It is particularly well suited for battery back-up nonvolatile memory application.

The UT62256 operates from a single 5V power supply and all inputs and outputs are fully TTL compatible.

PIN CONFIGURATION





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Sep.,2000

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ABSOLUTE MAXIMUM RATINGS*

PARAMETER	SYMBOL	RATING	UNIT
Terminal Voltage with Respect to V _{SS}	VTERM	-0.5 to +7.0	V
Operating Temperature	TA	0 to +70	$^{\circ}$ C
Storage Temperature	Tstg	-65 to +150	$^{\circ}\!\mathbb{C}$
Power Dissipation	Po	1	W
DC Output Current	lout	50	mA
Soldering Temperature (under 10 sec)	Tsolder	260	$^{\circ}$

^{*}Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.

TRUTH TABLE

MODE	CE#	OE#	WE#	I/O OPERATION	SUPPLY CURRENT
Standby	Ι	Χ	Χ	High - Z	ISB, ISB1
Output Disable	L	Н	Н	High - Z	Icc
Read	L	L	Н	Dout	Icc
Write	L	Х	L	Din	Icc

Note: H = V_{IH}, L=V_{IL}, X = Don't care.

DC ELECTRICAL CHARACTERISTICS (Vcc = $5V^{\pm}$ 10%, Ta = 0° C to 70° C)

PARAMETER	SYMBOL	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
Input High Voltage	ViH			2.2	-	Vcc+0.5	V
Input Low Voltage	VIL			- 0.5	-	0.8	V
Input Leakage Current	ILI	$V_{SS} \leq V_{IN} \leq V_{CC}$		- 1	-	1	μA
Output Leakage Current	ILO	$V_{SS} \leqq V_{I/O} \leqq V_{CC}$ CE#=V _{IH} or OE# = V _{IH} or WE# = V _{IL}		- 1	-	1	μA
Output High Voltage	Vон	I _{OH} = - 1mA		2.4	-	-	V
Output Low Voltage	Vol	$I_{OL} = 4mA$		-	-	0.4	V
Operating Power	Icc	CE# = V _{IL} , I _{I/O} = 0mA	- 35	-	60	100	mΑ
Supply Current		Cycle=Min.	- 70	-	40	70	mΑ
	IsB	CE# = V _{IH}		-	1	10	mA
Ctorodley Dayyan			normal				
Standby Power Supply Current	I _{SB1}	CE#≧Vcc-0.2V		-	0.3	5	mA
Supply Surrent	I _{SB}	CE# = V _{IH}	-L/- LL	-	-	3	mΑ
	I _{SB1}	CE#≧Vcc-0.2V	- L	-	2	100	μΑ
			- LL	-	1	50	μA

UT62256

32K X 8 BIT LOW POWER CMOS SRAM

CAPACITANCE (TA=25°C, f=1.0MHz)

PARAMETER	SYMBOL	MIN.	MAX	UNIT
Input Capacitance	CIN	-	8	pF
Input/Output Capacitance	C _{I/O}	-	10	pF

Note: These parameters are guaranteed by device characterization, but not production tested.

AC TEST CONDITIONS

Input Pulse Levels	0V to 3.0V
Input Rise and Fall Times	5ns
Input and Output Timing Reference Levels	1.5V
Output Load	$C_L = 100 pF, I_{OH}/I_{OL} = -1 mA/4 mA$

AC ELECTRICAL CHARACTERISTICS (Vcc = $5V\pm 10\%$, TA = 0° to 70°)

(1) READ CYCLE

PARAMETER	SYMBOL	UT62256-35		UT62256-70		UNIT
		MIN.	MAX.	MIN.	MAX.	Ī
Read Cycle Time	t _{RC}	35	-	70	-	ns
Address Access Time	taa	-	35	-	70	ns
Chip Enable Access Time	t _{ACE}	-	35	-	70	ns
Output Enable Access Time	toe	-	25	-	35	ns
Chip Enable to Output in Low Z	t _{CLZ*}	10	-	10	-	ns
Output Enable to Output in Low Z	tolz*	5	-	5	-	ns
Chip Disable to Output in High Z	t _{CHZ*}	-	25	-	35	ns
Output Disable to Output in High Z	t _{OHZ*}	-	25	-	35	ns
Output Hold from Address Change	tон	5	-	5	-	ns

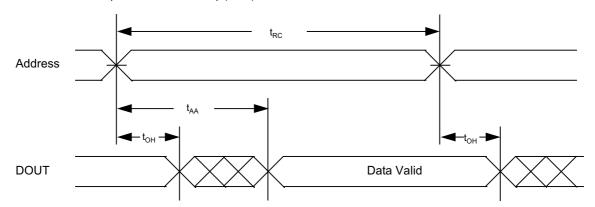
(2) WRITE CYCLE

PARAMETER	SYMBOL	UT622	UT62256-35		UT62256-70	
		MIN.	MAX.	MIN.	MAX.	
Write Cycle Time	twc	35	-	70	-	ns
Address Valid to End of Write	taw	30	-	60	-	ns
Chip Enable to End of Write	tcw	30	-	60	-	ns
Address Set-up Time	t _{AS}	0	-	0	-	ns
Write Pulse Width	twp	25	-	50	-	ns
Write Recovery Time	twr	0	-	0	-	ns
Data to Write Time Overlap	t _{DW}	20	-	30	-	ns
Data Hold from End of Write Time	t _{DH}	0	-	0	-	ns
Output Active from End of Write	tow*	5	-	5	-	ns
Write to Output in High Z	t _{WHZ*}	-	15	-	25	ns

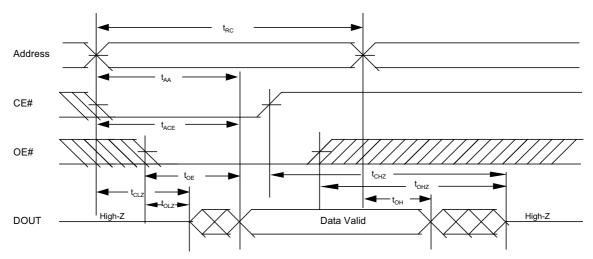
^{*}These parameters are guaranteed by device characterization, but not production tested.

TIMING WAVEFORMS

READ CYCLE 1 (Address Controlled) (1,2,4)



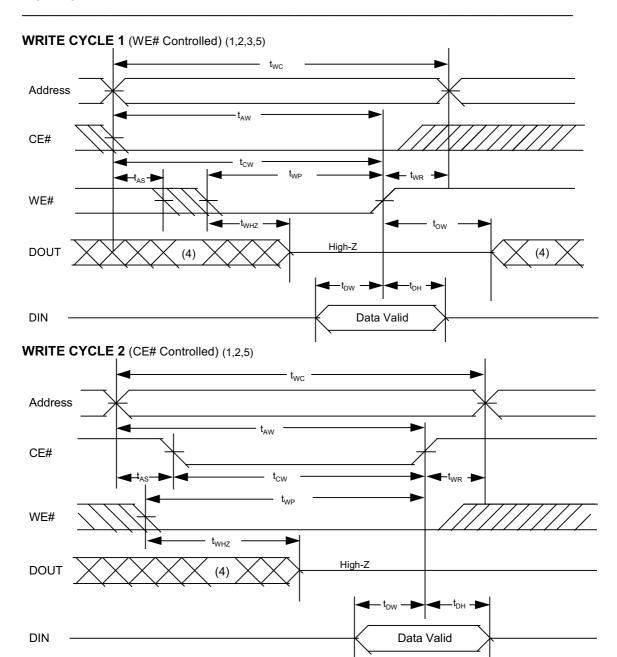
READ CYCLE 2 (CE# and OE# Controlled) (1,3,5,6)



Notes:

- 1. WE# is HIGH for read cycle.
- Device is continuously selected CE#=V_{IL}.
- 3. Address must be valid prior to or coincident with CE# transition; otherwise tAA is the limiting parameter.
- 4. OE# is LOW.
- 5. tcLz, tcLz, tcHz and toHz are specified with CL=5pF. Transition is measured \pm 500mV from steady state.
- 6. At any given temperature and voltage condition, tcHz is less than tcLz, toHz is less than toLz.

Rev 1.3



Notes:

- WE# or CE# must be HIGH during all address transitions.
 A write occurs during the overlap of a low CE# and a low WE#.
- 3. During a WE# controlled with write cycle with OE# LOW, twp must be greater than twnz+tow to allow the I/O

to turn off and data to be placed on the bus.

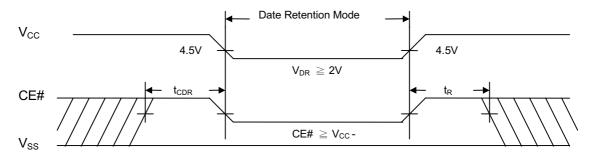
- 4. During this period, I/O pins are in the output state, and input singals must not be applied.
- 5. If the CE# LOW transition occurs simultaneously with or after WE# LOW transition, the outputs remain in a high impedance state.
- 6. t_{ow} and t_{wHz} are specified with CL=5pF. Transition is measured \pm 500mV from steady state.

DATA RETENTION CHARACTERISTICS (TA = 0° C to 70° C)

PARAMETER	SYMBOL	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
Vcc for Data Retention	V_{DR}	CE# \geq Vcc-0.2V		2.0	-	5.5	V
Data Retention Current	I _{DR}	Vcc=3V	- L	-	1	50	μA
		CE# \geq Vcc-0.2V	- LL	-	0.5	20	μA
Chip Disable to Data	tcdr	See Data Retention		0	-	-	ns
Retention Time		Waveforms (below)					
Recovery Time	t _R			tRC*	-	-	ns

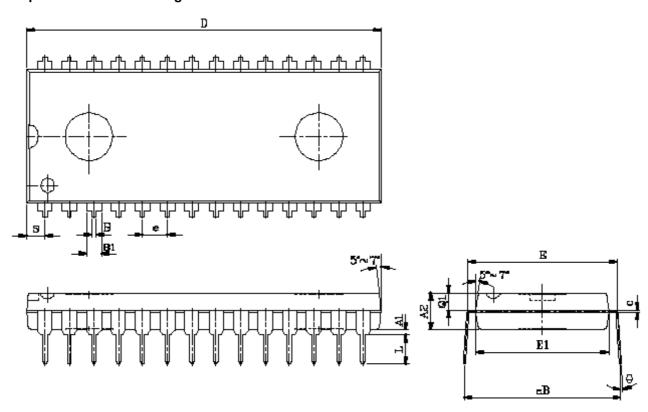
tRC* = Read Cycle Time

DATA RETENTION WAVEFORM



PACKAGE OUTLINE DIMENSION

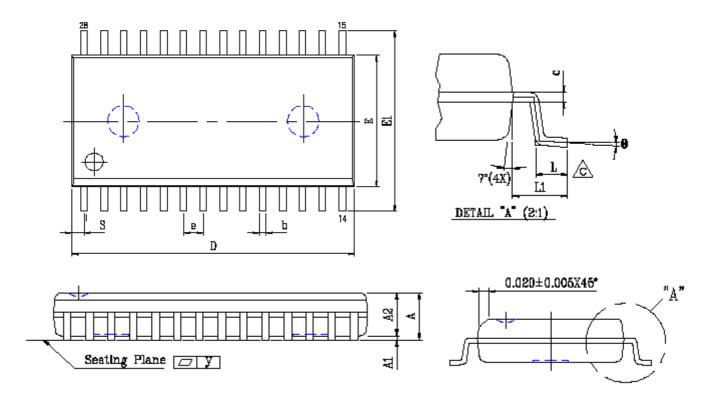
28 pin 600 mil PDIP Package Outline Dimension



	UNIT	INCH(BASE)	MM(REF)
	A1	0.010 (MIN)	0.254 (MIN)
	A2	0.150± 0.005	3.810± 0.127
	В	0.020 (MAX)	0.508(MAX)
	B1	0.055 (MAX)	1.397(MAX)
	С	0.012 (MAX)	0.304 (MAX)
	D	1.430 (MAX)	36.322 (MAX)
\triangle	E	0.625 (MAX)	15.87 (MAX)
	E1	0.52 (MAX)	13.208 (MAX)
	е	0.100 (TYP)	2.540(TYP)
	eB	0.6 (TYP)	15.24 (TYP)
	L	0.180(MAX)	4.572(MAX)
	S	0.06 (MAX)	1.524 (MAX)
	Q1	0.08(MAX)	2.032(MAX)
	θ	15°(MAX)	15°(MAX)

Rev 1.3

28 pin 330 mil SOP Package Outline Dimension

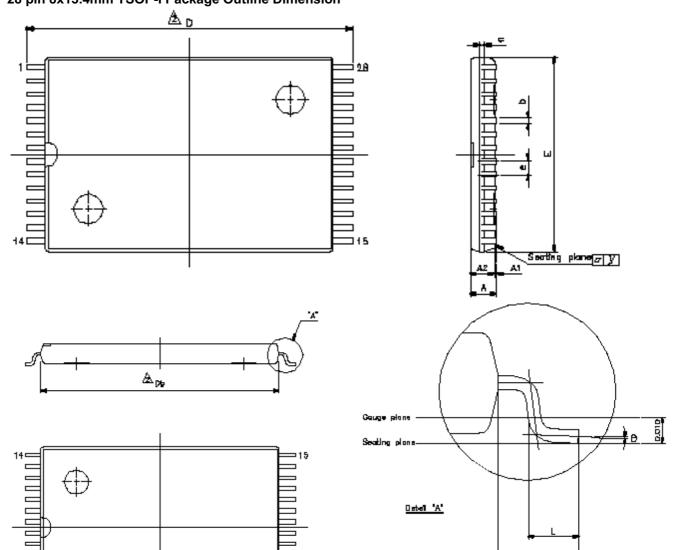


	UNIT SYMBOL	INCH(BASE)	MM(REF)
	Α	0.120 (MAX)	3.048 (MAX)
	A1	0.002(MIN)	0.05(MIN)
	A2	0.098± 0.005	2.489± 0.127
	b	0.015 (MIN)	0.38 (MIN)
	b	0.020 (MAX)	0.50 (MAX)
	С	0.010 (TYP)	0.254(TYP)
	D	0.728 (MAX)	18.491 (MAX)
	Е	0.350 (MAX)	8.890 (MAX)
7	E1	0.465± 0.012	11.811± 0.305
	е	0.050 (TYP)	1.270(TYP)
	L	0.05 (MAX)	1.270 (MAX)
_	L1	0.067± 0.008	1.702± 0.203
	S	0.047 (MAX)	1.194 (MAX)
7	У	0.003(MAX)	0.076(MAX)
	Θ	$0^{\circ} \sim 10^{\circ}$	$0^{\circ} \sim 10^{\circ}$

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28 pin 8x13.4mm TSOP-I Package Outline Dimension



Note:

E dimension is not including end flash The total of both sides' end flash is Not above 0.3mm.

	UNIT	INCH(BASE)	MM(REF)
	Α	0.047 (MAX)	1.20 (MAX)
	A1	0.004± 0.002	0.10± 0.05
	A2	0.039± 0.002	1.00± 0.05
	b	0.006 (TYP)	0.15(TYP)
	С	0.010 (TYP)	0.254(TYP)
$\sqrt{2}$	Db	0.465± 0.004	11.80± 0.10
	Е	0.315± 0.004	8.00± 0.10
_	е	0.022 (TYP)	0.55(TYP)
$\sqrt{2}$	D	0.528± 0.008	13.40± 0.20
$\sqrt{2}$	L	0.020± 0.004	0.50± 0.10
$\sqrt{}$	L1	0.0315± 0.004	0.80± 0.10
$\sqrt{5}$	у	0.08(MAX)	0.003(MAX)
	θ	0°∼5°	$0^{\circ}\sim5^{\circ}$
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ORDERING INFORMATION

PART NO.	ACCESS TIME	STANDBY CURRENT	PACKAGE
	(ns)	(μ Α)	
UT62256PC-70	70	5mA	28PIN PDIP
UT62256PC-70L	70	100 _µ A	28PIN PDIP
UT62256PC-70LL	70	50 µA	28PIN PDIP
UT62256SC-35	35	5mA	28PIN SOP
UT62256SC-35L	35	100 _µ A	28PIN SOP
UT62256SC-35LL	35	50 _µ A	28PIN SOP
UT62256SC-70	70	5mA	28PIN SOP
UT62256SC-70L	70	100 µA	28PIN SOP
UT62256SC-70LL	70	50 _µ A	28PIN SOP
UT62256LS-35L	35	100 µA	28PIN STOP-I
UT62256LS-35LL	35	50 µA	28PIN STOP-I
UT62256LS-70L	70	100 µA	28PIN STOP-I
UT62256LS-70LL	70	50 µA	28PIN STOP-I